



3D Packaging and Integration Japan TC Chapter

Japan Standards Winter 2021 Meetings

Friday, October 22, 2021,

Web conference

14:00-17:00

AGENDA

1 Welcome / Call to Order

1.1 Introductions

1.2 Meeting Reminders (Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting of 3D Packaging & Integration Japan TC Chapter

3 Liaison Report

3.1 NA TC Chapter

3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

None

6 Task Force & Study Group Reports

6.1 GCS

6.2 3D Packaging & Integration 5 Year Review Task Force

6.3 3DS IC Bonded Layer Inspection Metrology Task Force

6.4 450 mm Assembly & Test Die Preparation (ATDP) Task Force

6.5 Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging Task Force

6.6 Panel Level Packaging (PLP) Glass Carrier Task Force

6.7 3D Packaging & Integration Steering Group

7 Old Business

7.1 Project Period Review

7.2 5 Year Review Check



8 New Business

9 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10 Next Meeting and Adjournment